

MN4013B/MN4013BS

Dual D-Type Flip-Flop

Outline

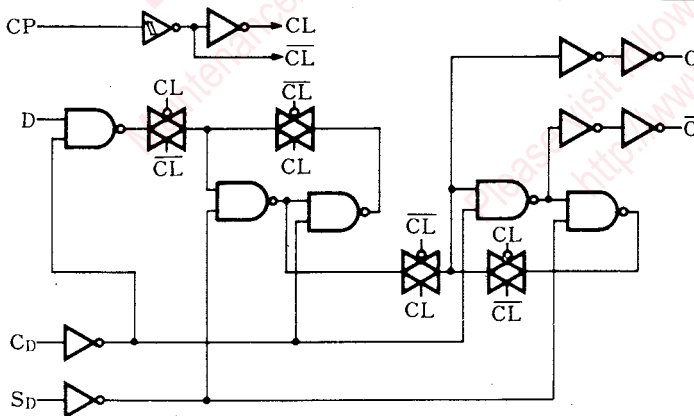
The MN4013B/S has 2 built-in circuits of D-type flip-flops in one chip. The respective flip-flop has independent data, set, clear, and clock inputs and complementary outputs (O , \bar{O}). The input applied to the data input is transmitted to the O output and \bar{O} output at the rise of the clock pulse. The logic state is held to "H" or "L" by the clock level. This MN4013B/S is equivalent to Motorola's MC14013B and RCA's CD4013B.

Truth Table

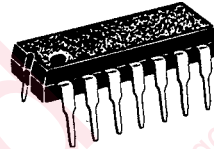
Input				Output	
S_D	C_D	CP	D	O_{n+1}	\bar{O}_{n+1}
H	L	×	×	H	L
L	H	×	×	L	H
H	H	×	×	H	H
L	L		×	O_n	\bar{O}_n
L	L		L	L	H
L	L		H	H	L

Note) × : don't care

Logic Diagram

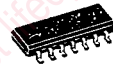


P-1



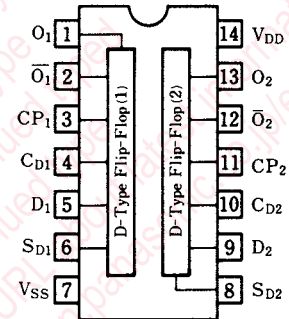
14-pin plastic DIL package

P-2



14-pin PANAFLAT package (SO-14D)

Pin Configuration



Pin description

- S_D : Data set input
- C_D : Data clear input
- D : Data input
- CP : Clock input
- O, \bar{O} : Output (complementary)

■ Absolute Maximum Ratings (Ta=25°C)

Item	Symbol	Rating	Unit
Supply voltage	V _{DD}	-0.5~+18	V
Input voltage	V _I	-0.5~V _{DD} +0.5*	V
Output pin voltage	V _O	-0.5~V _{DD} +0.5*	V
Peak input · output pin current	±I _I	max. 10	mA
Power dissipation (per package)	Ta=-40~+60°C	max. 400	mW
	Ta=+60~+80°C	Decrease to 200mW at the rate of 8mW/°C	
Power dissipation (per output pin)	P _D	max. 100	mW
Operating ambient temperature	T _{opr}	-40~+85	°C
Storage temperature	T _{stg}	-65~+150	°C

* V_{DD}+0.5V should be lower than 18V.

■ DC Characteristics (V_{SS}=0V)

Item	V _{DD} (V)	Symbol	Condition	Ta=-40°C		Ta=25°C		Ta=85°C		Unit	
				min.	max.	min.	max.	min.	max.		
Static supply current	5	I _{DD}	V _I =V _{SS} or V _{DD}	—	4	—	4	—	30	μA	
	10			—	8	—	8	—	60		
	15			—	16	—	16	—	120		
Output voltage low level	5	V _{OL}	V _I =V _{SS} or V _{DD} I _O <1μA	—	0.05	—	0.05	—	0.05	V	
	10			—	0.05	—	0.05	—	0.05		
	15			—	0.05	—	0.05	—	0.05		
Output voltage high level	5	V _{OH}	V _I =V _{SS} or V _{DD} I _O <1μA	4.95	—	4.95	—	4.95	—	V	
	10			9.95	—	9.95	—	9.95	—		
	15			14.95	—	14.95	—	14.95	—		
Input voltage low level	5	V _{IL}	I _O <1μA	V _O =0.5V or 4.5V		—	1.5	—	1.5	V	
	10			V _O =1V or 9V		—	3	—	3		
	15			V _O =1.5V or 13.5V		—	4	—	4		
Input voltage high level	5	V _{IH}	I _O <1μA	V _O =0.5V or 4.5V		3.5	—	3.5	—	V	
	10			V _O =1V or 9V		7	—	7	—		
	15			V _O =1.5V or 13.5V		11	—	11	—		
Output current low level	5	I _{OL}	V _O =0.4V, V _I =0 or 5V		0.52	—	0.44	—	0.36	mA	
	10		V _O =0.5V, V _I =0 or 10V		1.3	—	1.1	—	0.9		
	15		V _O =1.5V, V _I =0 or 15V		3.6	—	3	—	2.4		
Output current high level	5	-I _{OH}	V _O =4.6V, V _I =0 or 5V		0.52	—	0.44	—	0.36	mA	
	10		V _O =9.5V, V _I =0 or 10V		1.3	—	1.1	—	0.9		
	15		V _O =13.5V, V _I =0 or 15V		3.6	—	3	—	2.4		
Output current high level	5	-I _{OH}	V _O =2.5V, V _I =0 or 5V		1.7	—	1.4	—	1.1	mA	
Input leakage current	15	±I _I	V _I =0 or 15V		—	0.3	—	0.3	—	1	μA

■ Switching Characteristics (Ta=25°C, VSS=0V, CL=50pF)

Item	VDD(V)	Symbol	min.	typ.	max.	Unit
Output rise time (Fig. 1)	5	t _{TLH}	—	60	180	ns
	10		—	30	90	
	15		—	20	60	
Output fall time (Fig. 1)	5	t _{THL}	—	60	180	ns
	10		—	30	90	
	15		—	20	60	
Minimum data set-up time	5	t _{su}	—	30	90	ns
	10		—	10	30	
	15		—	10	30	
Maximum clock rise time	5	trφ, tfφ	20	—	—	μs
Maximum clock fall time	10		2.5	—	—	
	15		1	—	—	
Maximum clock frequency	5	f _{max}	6	12	—	MHz
	10		12	25	—	
	15		18	36	—	
Propagation time (Fig. 1) (CP-O, \bar{O})	5	t _{PLH}	—	100	300	ns
	10		—	40	120	
	15		—	30	90	
Propagation time (Fig. 1) (CP-O, \bar{O})	5	t _{PHL}	—	110	330	ns
	10		—	45	135	
	15		—	30	90	
Propagation time (Fig. 2) (C _D , S _D -O, \bar{O})	5	t _{PLH}	—	135	405	ns
	10		—	50	150	
	15		—	35	105	
Propagation time (Fig. 2) (C _D , S _D -O, \bar{O})	5	t _{PHL}	—	100	300	ns
	10		—	40	120	
	15		—	30	90	
Minimum clear pulse width (Fig. 2)	5	t _{wCD}	—	45	135	ns
Minimum pre-set pulse width	10	t _{wSD}	—	20	60	
	15		—	20	60	
Input capacitance		C _i	—	—	7.5	pF

● Switching waveforms

Fig. 1 t_{TLH}, t_{PLH} (CO-O, \bar{O})

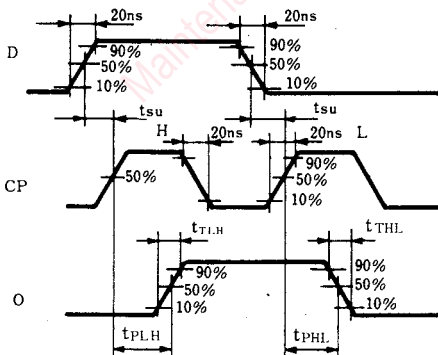
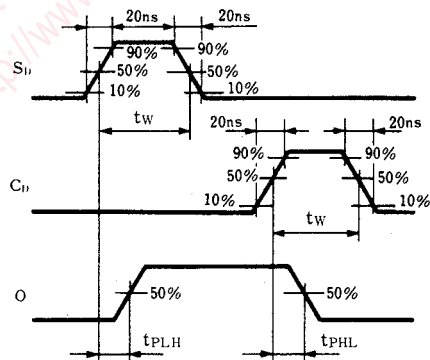


Fig. 2 t_{TLH}, (S_D-O, C_D- \bar{O}), t_{PLH} S_D-O, C_D- \bar{O}), t_{wCD}, t_{wSD}



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